



# SOT758-3

plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.85 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN16
<b>Package type industry code</b>	HVQFN16
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-220
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	8-2-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	0.85	0.9	mm
A <sub>2</sub>	package height	[tbd]	-	0.85	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	16	-	

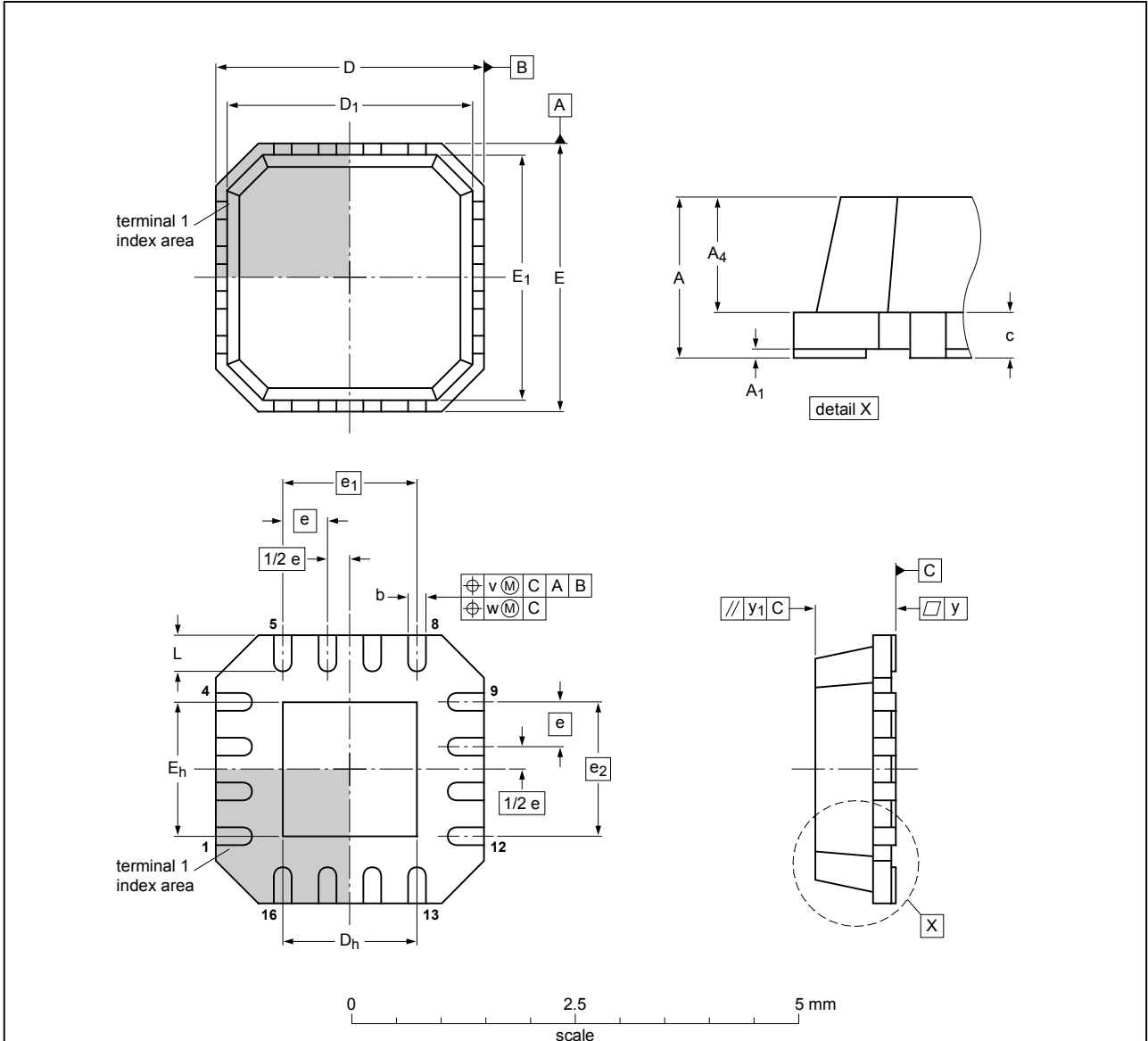


plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.85 mm

## 2. Package outline

HVQFN16: plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1</sub>	A <sub>4</sub>	b	c	D	D <sub>1</sub>	D <sub>h</sub>	E	E <sub>1</sub>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	0.9	0.05 0.00	0.7 0.6	0.30 0.18	0.2	3.1 2.9	2.85 2.65	1.6 1.4	3.1 2.9	2.85 2.65	1.6 1.4	0.5	1.5	1.5	0.5 0.3	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT758-3		MO-220				07-10-11 08-02-08

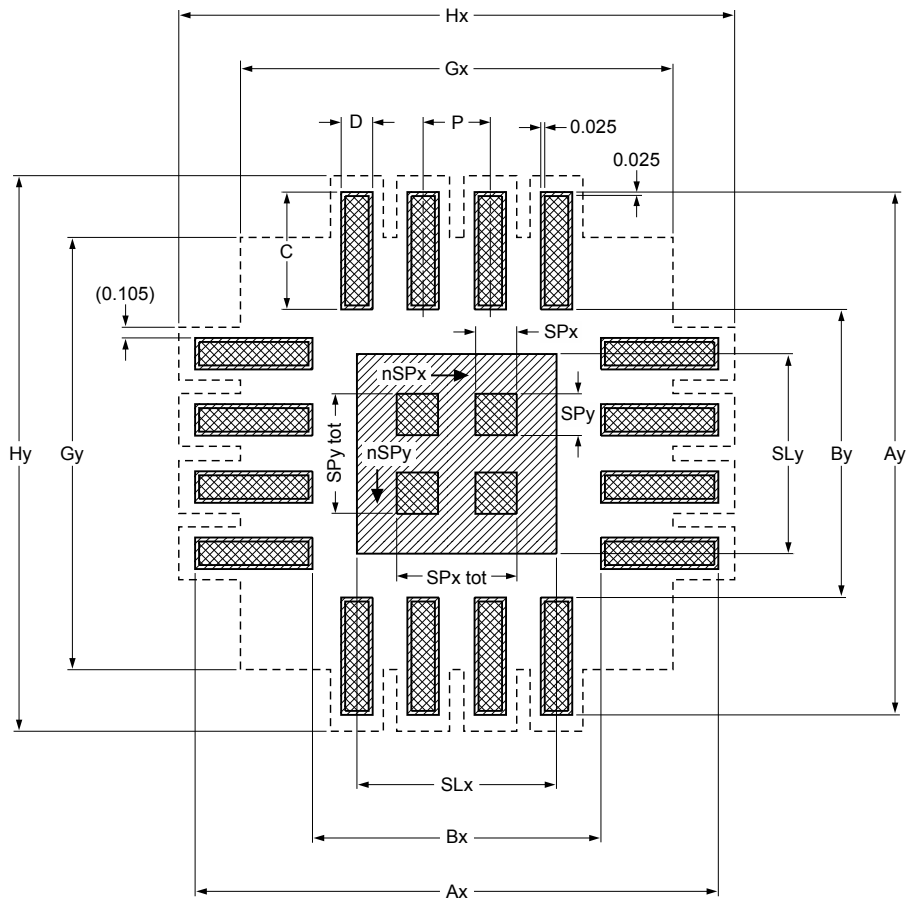
Fig. 1. Package outline HVQFN16 (SOT758-3)

plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.85 mm

### 3. Soldering

Footprint information for reflow soldering of HVQFN16 package

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- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area

nSPx	nSPy
2	2

Dimensions in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.50	4.00	4.00	2.20	2.20	0.90	0.24	1.50	1.50	0.90	0.90	0.30	0.30	3.30	3.30	4.25	4.25

Issue date ~~09-06-15~~  
12-03-11

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Fig. 2. Reflow soldering footprint for HVQFN16 (SOT758-3)

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## 4. Legal information

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